

RoHS								
Specification								
Client Name:								
Client P/N: Factory P/N: <u>HL-AF-5060U32YC-3-</u> S1-T1								
Sending Date:								
Cl	ient appro	val	Hong li approval					
Approval	Audit	Confirmation	Approval	Audit	Confirmation			
			殷小平	N HI	王佩			
□ Qualified □ Unqualified DATE: 工程部								
 Adr: West side of Dongfeng Highway, Auto City, Huadu District, Guangzhou, China Tel: 020-86733333 (Switchboard) Fax: 020-86733883 86733938 86733265 Web: www.honglitronic.com 								



Features

- Extremely wide viewing angle
- Suitable for all SMT assembly and solder process
- Available on tape and reel
- Moisture sensitivity level: Level 4
- Package:1000pcs/reel
- RoHS compliant

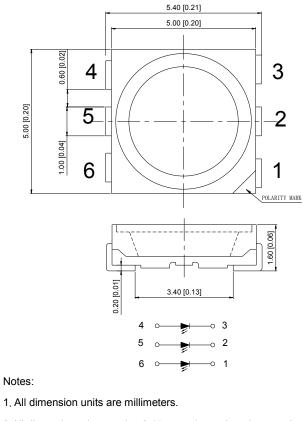
Description

The Yellow source color devices are made with AlGaInP on Substrate Light Emitting Diode

Applications

- Optical indicator
- Indoor display
- Interior automotive lighting
- Backlight for LCD, switch and Symbol, display
- Light pipe application
- General use

Package Dimensions



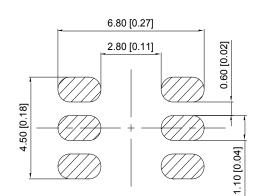
2.All dimension tolerance is ± 0.15 mm unless otherwise noted.





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Recommended Soldering Pattern





Selection Guide

Part No.	Dice	Lens Type	Luminous in @ 20i	Viewing Angle	
i ur no.	2.00	Min.		Тур.	201/2
HL-AF-5060U32YC-3-S1 -T1	Yellow (AlGaInP)	Water Clear	1700	2200	120 °

Note:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2.the above luminous intensity measurement allowance tolerance ±10%.

Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Min.	Тур.	Max	Units	Test Conditions
Forward Voltage	VF	1.8		2.4	V	IF=20mA *3
Reverse Current	lR			10	uA	VR = 5V
Dominate Wavelength	λd	586		596	nm	I⊧=20mA *3

Absolute Maximum Ratings at Ta=25°C

Parameter	Rating	Units
Power dissipation	225	mW
DC Forward Current per chip	30	mA
Peak Forward Current [1]	300	mA
Reverse Voltage	5	V
Electrostatic Discharge (HBM)	2000	V
Operating Temperature	-40 ~ +85	°C
Storage Temperature	-40 ~ +100	°C

Note:

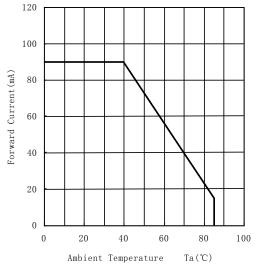
1.1/10 Duty Cycle, 0.1ms Pulse Width.

2. The above forward voltage measurement allowance tolerance $\pm 0.1V$

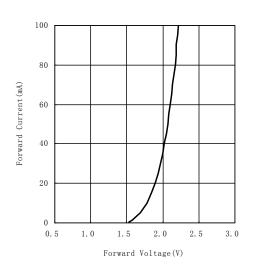


Typical optical characteristics curves

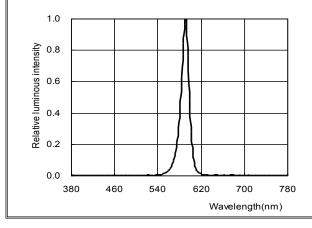
Ambient Temperature VS. Forward Current



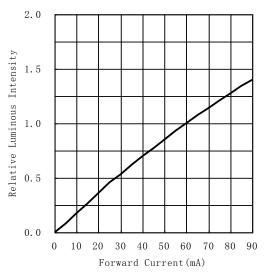
Forward Voltage VS. Forward Current



Relative spectral emission



Forward Current VS. Relative Intensity



Ambient Temperature VS. Relative Intensity

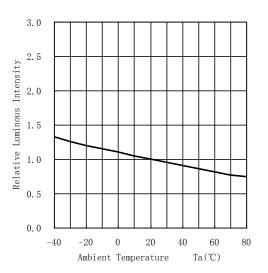
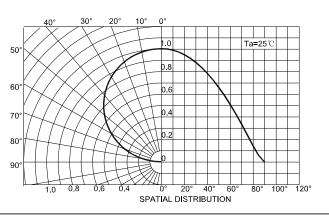


Diagram characteristics of radiation



DATE: OCT/07/2011



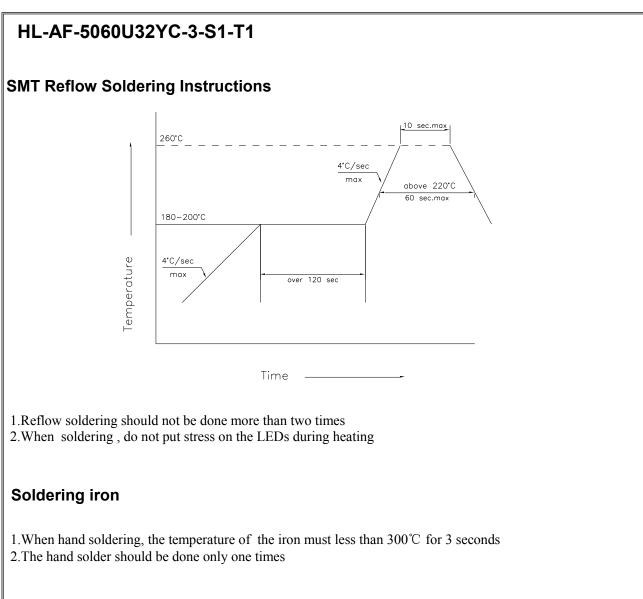
Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below. Confidence level :90% LTPD :10%

No.	Items	Ref.Standard	Test Condition	Test Hours/ Cycles	Sample Size	Ac/Re
1	Reflow	JESD22-B106	Temp:260℃max T=10 sec	3 times.	22Pcs.	0/1
2	Temperature Cycle	JESD22-A104	100℃±5℃ 30 min. ↑↓5 min -40℃±5℃ 30 min.	100 Cycles	22Pcs.	0/1
3	Thermal Shock	JESD22-A106	100℃±5℃ 5 min. ↑↓ -40℃±5℃ 5 min.	100 Cycles	22Pcs.	0/1
4	High Temperature Storage	JESD22-A103	Temp:100℃±5℃	1000Hrs.	22Pcs.	0/1
5	Low Temperature Storage	JESD22-A119	Temp:-40℃±5℃	1000Hrs.	22Pcs.	0/1
6	DC Operating Life	JESD22-A108	Ta=25 ୯ ±5 ୯ IF=60mA	1000Hrs.	22Pcs.	0/1
7	High Temperature High Humidity	JESD22-A101	85℃±5℃/ 85%RH IF=15mA	1000Hrs.	22Pcs.	0/1

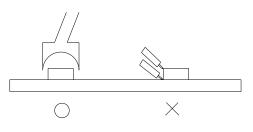
*The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.





Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of LEDs will or will not be damaged by repairing.

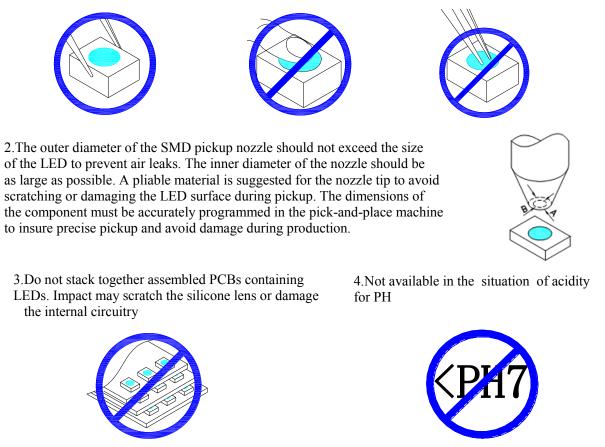




Handling Precautions

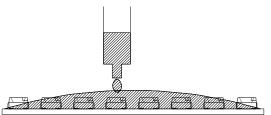
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, Special handling precautions need to be observed during assemble using silicone encapsulated LED products, Failure to comply might leads to damage and premature failure of the LED.

1.Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.



5.LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating

6.When we need to use external glue for LED application products, please make sure that the external glue matches the LED packaging glue. Additionally ,as most of LED packaging glue is silica gel, and it has strong Oxygen permeability as well as strong moisture permeability; in order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the single content in the external glue of the application products is required to be less than 1500PPM



7. Other points for attention, please refer to our LED user manual.



